



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PDIP 8-28 LEAD

Stress	Sample Size	Device Hr./Cyc	Condition	Total Fails	Fail Percentage
85/85	200	10,000	85°C, 85%RH	0	0.00
BOND INT	375	227,500	200°C + N2	0	0.00
HAST	2,090	206,5750	130°C, 85%RH	0	0.00
Pressure Pot	4,990	488,640	121°, 15 PSIG	0	0.00
Solder DUNK	40	120	260°C, 10SEC	000.00	0.00
Solderability	1,105	8,960	883 M2003	0	0.00
Temp Cycle	5,245	2,037,500	-65°C-150°C	0	0.00